

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of Takayama et al.		)	I hereby certify that this correspondence is being deposited
		) )	with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on
Serial No.: 09/598,736		)	February 21, 2006
Filed: June 21, 2000		) )	(Date of Deposit)  Cristine M. Noll  Name of applicant, assignee, or Registered Rep.
For:	Wiring Material, Semiconductor Device Provided With A Wiring Using The Wiring Material And Method Of Manufacturing The	•	Signature Date
Art Unit: 2811		)	
Examiner: Hung K. Vu		)	
P. O. 1	nissioner for Patents Box 1450 ndria, VA 22313-1450		

## **AMENDMENT (F) AFTER FINAL**

Sir:

In furtherance of Amendment E filed on January 18, 2006 in response to the Final Rejection of October 18, 2006, a RCE and one month extension of time being submitted herewith, please amend the above-identified application as follows: